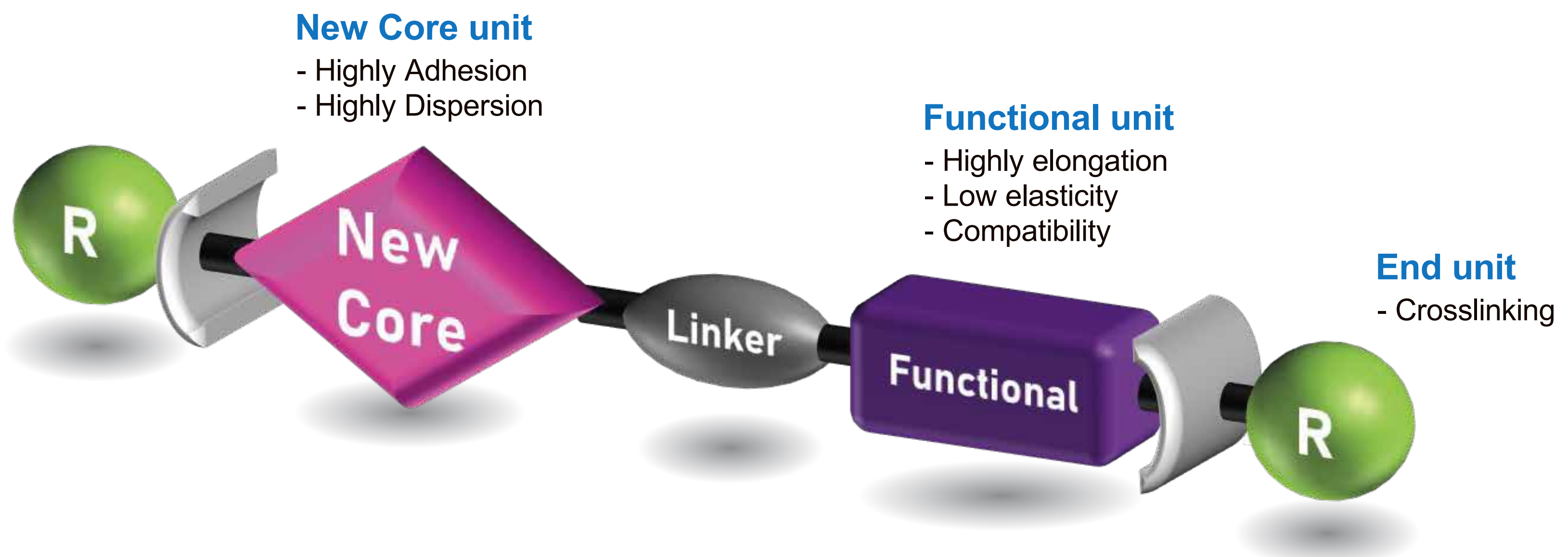


AD series

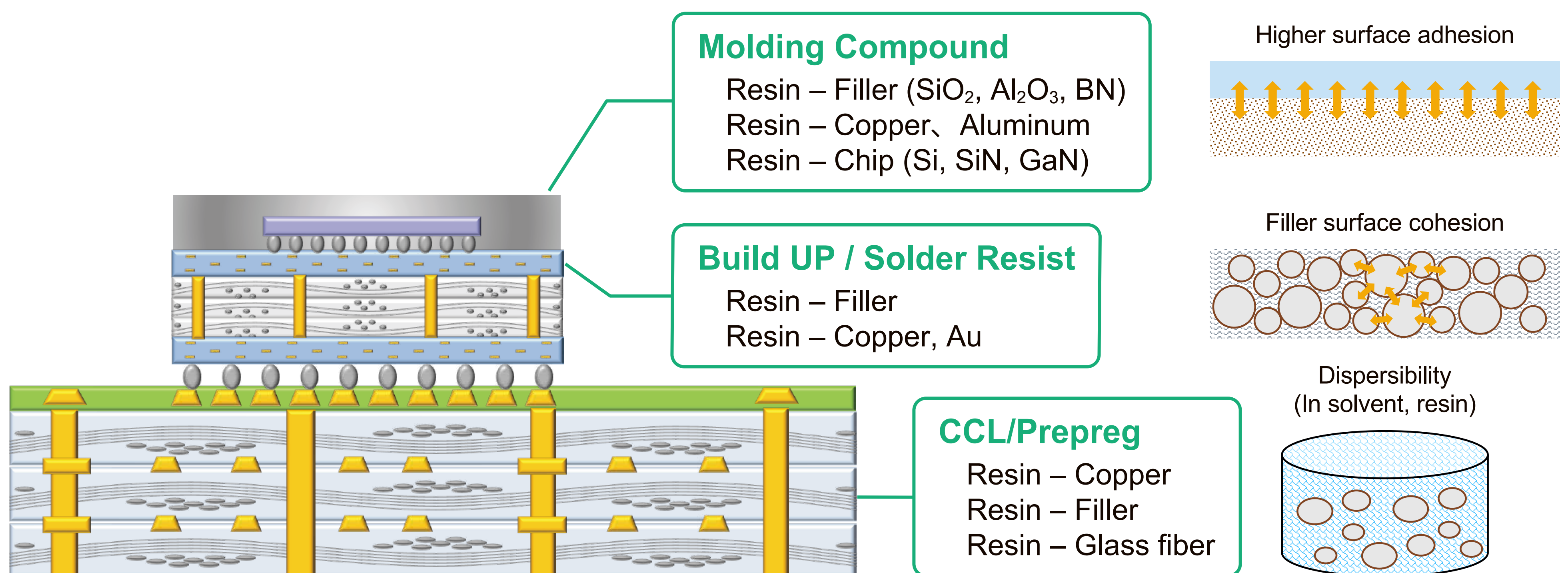
Highly Adhesive, Highly Dispersive Materials

-Expected applications : Next-generation electronics-

Design Concept



Application



Product list

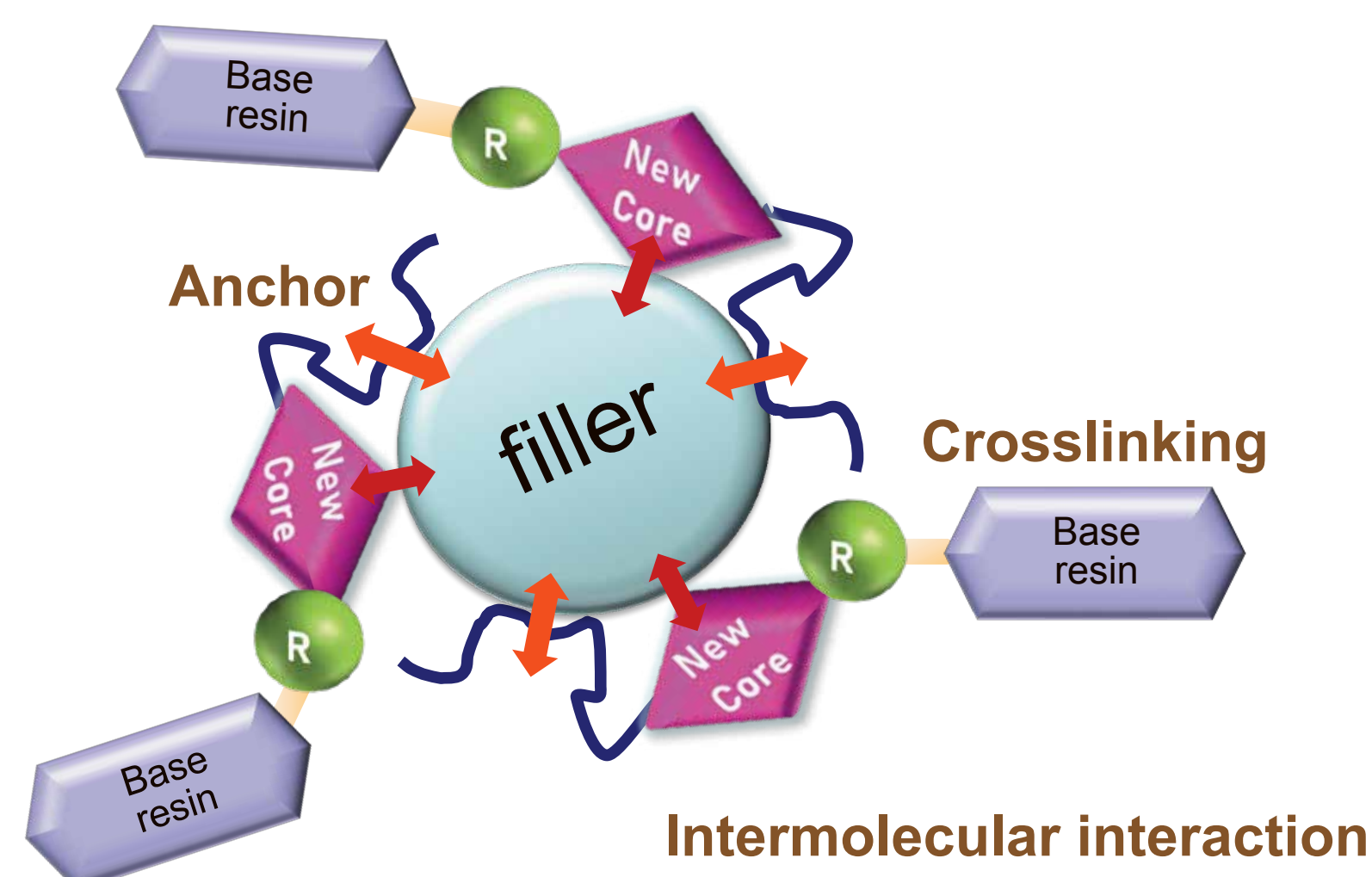
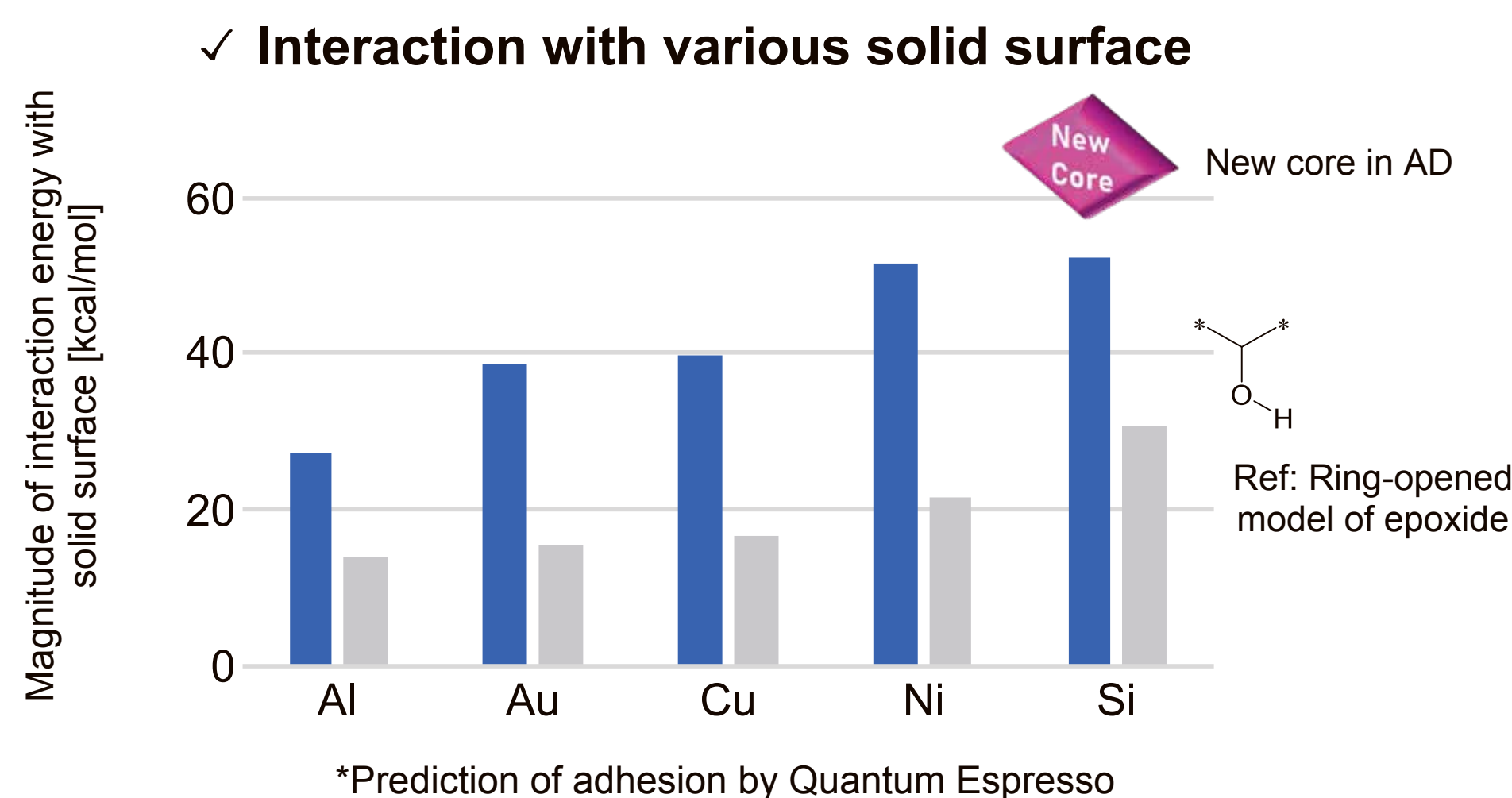
	AD1017	AD1019	AD1020
	High adhesion High dispersion Low modulus Epoxy reactivity	High adhesion High dispersion High compatibility Epoxy reactivity	High adhesion High dispersion High compatibility Radical reactivity
Functional	Type-α	Type-β	Type-β
R	Phenol	Phenol	Allyl
Non-volatile (%)	30	30	30
Solvent	MEK/Toluene	MEK/Toluene	MEK/Toluene
Viscosity (mPa · s@25 °C)	15~25	15~25	15~25
Stage	Pilot	Pilot	R&D

AD series

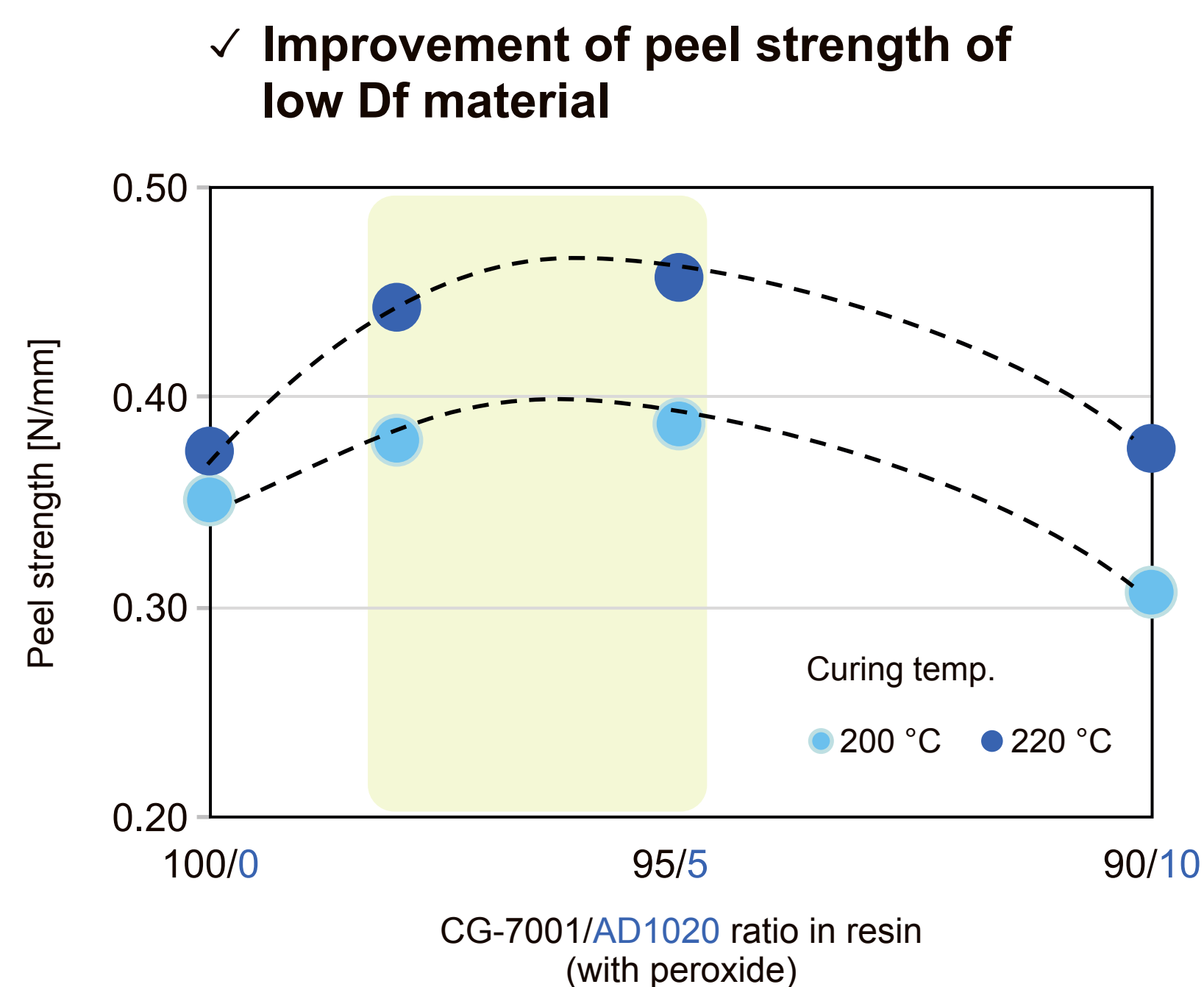
Highly Adhesive, Highly Dispersive Materials

-Expected applications : Next-generation electronics-

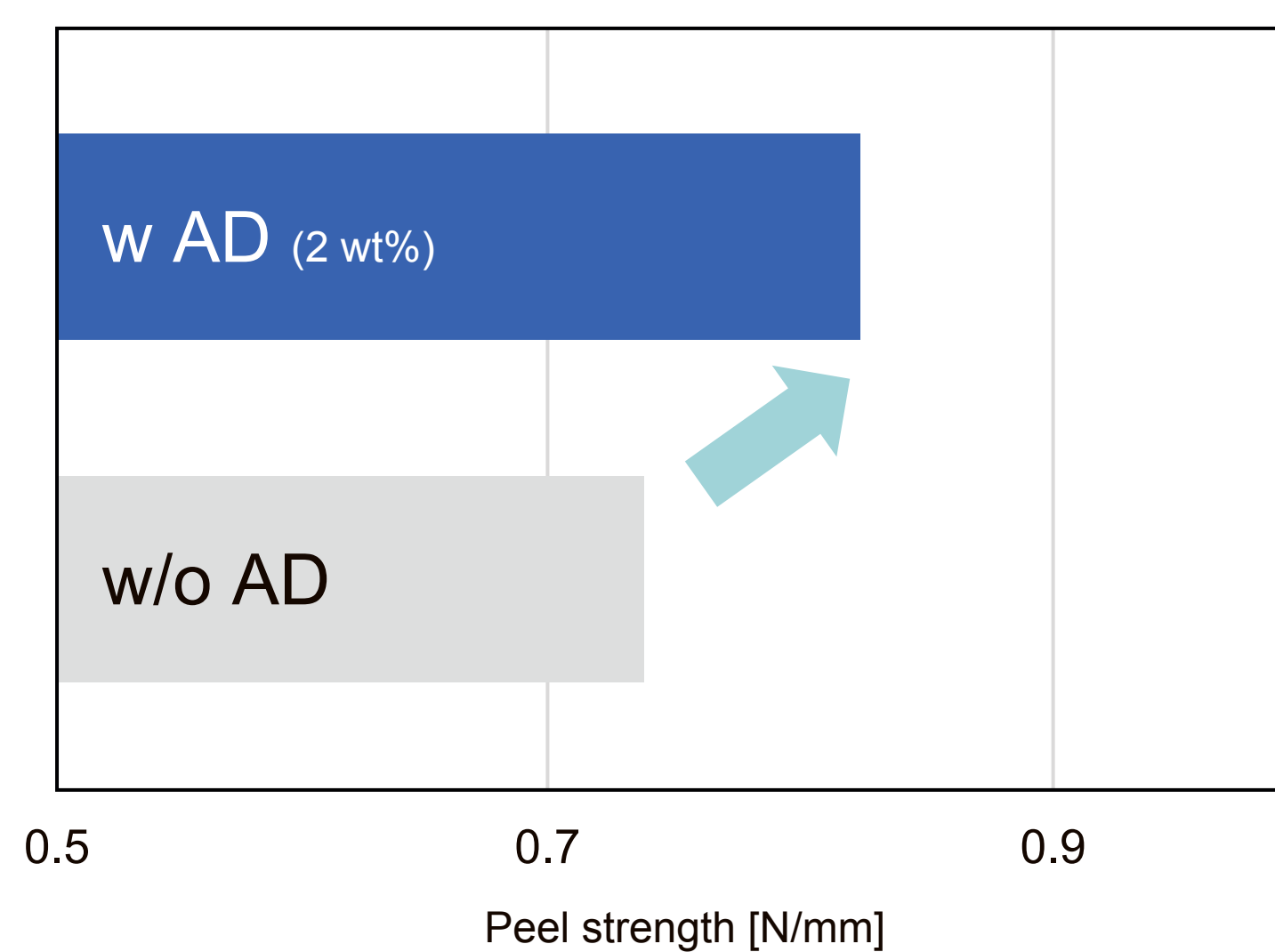
New Core



Improvement of Adhesion with Cu



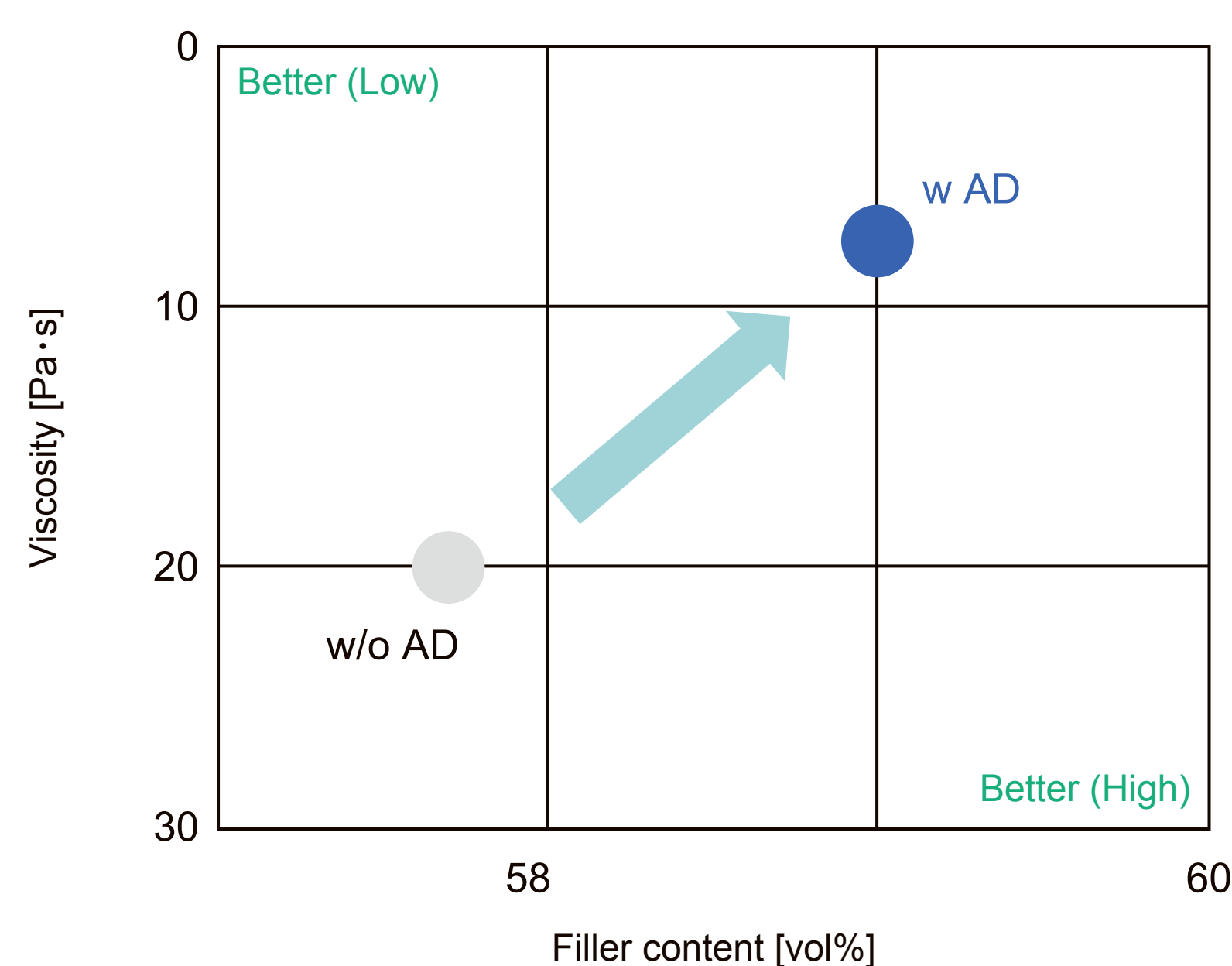
✓ Improvement of peel strength of composition with high filler content



w AD: AD1019/Epoxide/Phenolic resin/ Al_2O_3 (2 μm)
w/o AD: Epoxide/Phenolic resin/ Al_2O_3 (2 μm)
* Al_2O_3 content: 80 wt%

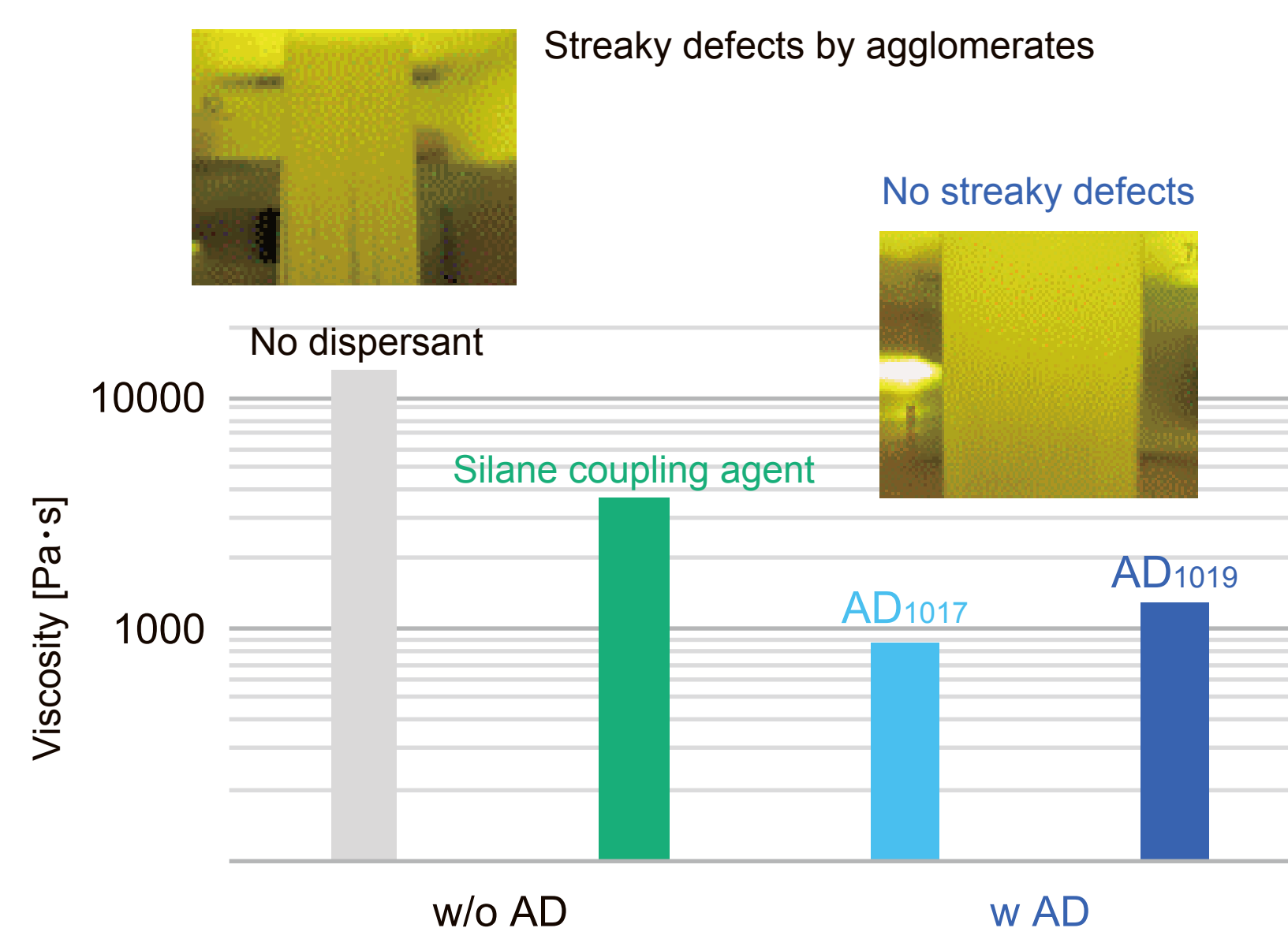
Improvement of filler Dispersion

- ✓ Higher filler content
- ✓ Lower viscosity



Non-solvent dispersion
w AD: AD1017/Epoxide/ SiO_2 (1.5 μm)
w/o AD: Viscosity modifier/Epoxide/ SiO_2 (1.5 μm)
*Viscosity of both vehicle: Adjusted to 0.4 Pa·s

- ✓ Better uniformity
- ✓ Lower viscosity



No dispersant: BN+ SiO_2
With dispersant: [BN+ SiO_2]/AD or Silane coupling agent=93/7